

LISTING OF THE CLAIMS

This listing of claims, amended as indicated below, will replace all prior versions, and listings, of claims in the application

1. (Canceled)
2. (Previously Presented) An apparatus as claimed in claim 21, wherein the predetermined distance is determined by considering one or more factors in the group consisting of the thickness, size and elastic modulus of the die, the thickness and elastic modulus of the film, the interfacial adhesive strength between the die and the elastic surface of the film and the shape and size of the ejector pin.
3. (Previously Presented) An apparatus as claimed in claim 21, wherein the predetermined distance is less than 1.2 mm from the edges of the die where the die is a silicon die of between 3 mm to 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.
4. (Previously Presented) An apparatus as claimed in claim 21, wherein the predetermined distance is less than 1.6 mm from the edges of the die where the die is a silicon die of greater than 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.
5. (Previously Presented) An apparatus as claimed in claim 21, wherein the predetermined distance is less than 0.5 mm from the edges of the die where the die is a gallium arsenide die of between 3 mm to 8 mm in width and less than 0.15 mm thickness, the film has a thickness of approximately 0.1 mm and an interfacial adhesive strength between the die and the adhesive surface is less than 15 Joules per meter square.

6. (Previously Presented) An apparatus as claimed in claim 21, including a vacuum ejector platform for supporting a portion of the film on which the die to be detached is mounted while the film is contacted by the ejector device.

7. (Original) An apparatus as claimed in claim 6, including apertures corresponding substantially to positions of each corner of the die to be detached, wherein the ejector pins are houseable within the vacuum ejector platform and projectable through said apertures for contacting the die.

8. (Previously Presented) An apparatus as claimed in claim 21, wherein the ejector device comprises at least four ejector pins, each ejector pin corresponding to a position substantially at a corner of the die.

9. (Original) An apparatus as claimed in claim 8, including one or more ejector pins corresponding to a position substantially at a center portion of the die.

10. (Previously Presented) An apparatus as claimed in claim 21, wherein each ejector pin has an effective support area of at least $1 \times 10^{-4} \text{ mm}^2$.

11-20. (Canceled).

21. (Currently Amended) An apparatus for detachment of a thin die from a film, the film having an adhesive surface on which a plurality of dice are mounted, the apparatus comprising: an ejector device comprising a plurality of ejector pins, the ejector pins being operative to initiate detachment of a die from the film by contacting the film under the die on a second surface of the film opposite the adhesive surface substantially at the corners of the die within a predetermined distance from the edges of said die and by raising the film under the corners of the die to separate the film under the corners of die is separated from the die; and

a collet operative to detach the die from the film after detachment has been initiated by the ejector device, and to hold the die after detachment from the film.

22. (Previously Presented) An apparatus as claimed in claim 9, wherein the ejector pins which contact the film substantially under the center portion of the die, do not make contact with the film before the ejector pins which contact the film substantially at the corners of the die.